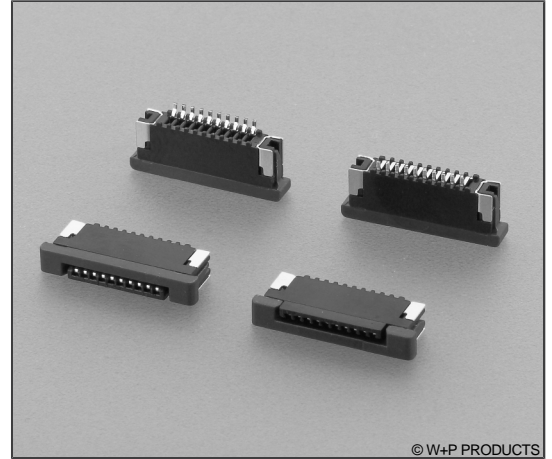


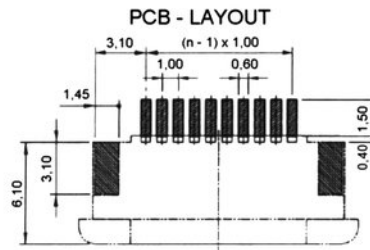
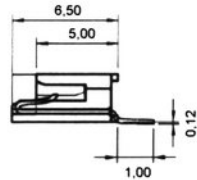
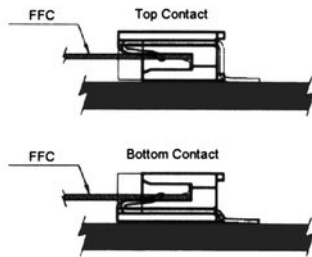
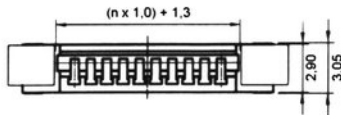
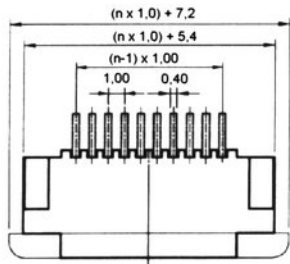
### Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Zinn über Nickel <i>Tin plated over nickel</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20mΩ < 20mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 500MΩ > 500MΩ
Spannungsfestigkeit <i>Test Voltage</i>	300V <sub>AC</sub> 300V <sub>AC</sub>
Nennspannung <i>Voltage Rating</i>	60V <sub>AC</sub> 60V <sub>AC</sub>
Nennstrom <i>Current Rating</i>	0,5A 0,5A
Temperaturbereich <i>Temperature Range</i>	-40°C ... +105°C -40°C ... +105°C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

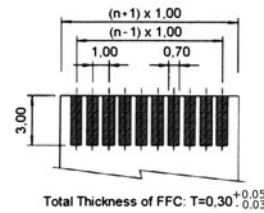


© W+P PRODUCTS

Passende Flex-Kabel:  
Compatible Flexible Flat Cables:  
**599**



Recommended Flexible Flat Cable (FFC)



Series

**5531**

Contacts\*

**10**

04-30

Type\*

**10**

10 Kontakte oben  
Top contacts  
20 Kontakte unten  
Bottom contacts

Packaging\*

**ST**

ST  
TR (Option)

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

### Lieferformen / Packaging Options:

**ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
**TR (Option)** Tape & Reel / Tape & Reel

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

